[ABSTRACT]

A bonding apparatus (100) having an optical system (20), an imaging element (70) for acquiring an image formed by the optical system (20) as a picture (14), an illumination unit (30) for illuminating an electronic component (13), and a control part (80) for processing the image acquired by the imaging element (70), the control part (80) illuminating the electronic component (13) through a first inclined optical path inclined with respect to the optical axis (24) of a first portion of the optical system (20) facing the electronic component (13) and acquiring a first image, illuminating the electronic component (13) through a second inclined optical path inclined toward the opposite side from the first inclined optical path with respect to the optical axis (24) of the first portion and acquiring a second image of the electronic component (13) as a subject, and calculating an amount of variation from a reference height of the electronic component (13) on the basis of the positional offset amount between the first image and the second image. The height of a subject or a component of the bonding apparatus can thereby be detected by a simple method.

FIGURE 1